



Material Content Data Sheet



Sales Product Name	TLD5542-1QV			Issued		14. November 2019		
MA#	MA005401464							
Package	PG-VQFN-48-31			Weight*		129.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.790	1.38	1.38	13847	13847
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		139	
	non noble metal	zinc	7440-66-6	0.072	0.06		554	
	non noble metal	iron	7439-89-6	1.433	1.11		11085	
	non noble metal	copper	7440-50-8	58.193	45.01	46.19	450090	461868
wire	non noble metal	copper	7440-50-8	0.629	0.49	0.49	4865	4865
encapsulation	organic material	carbon black	1333-86-4	0.190	0.15		1469	
	plastics	epoxy resin	-	8.041	6.22		62190	
	inorganic material	silicondioxide	60676-86-0	55.081	42.60	48.97	426023	489682
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20082	20082
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4748	4748
glue	plastics	epoxy resin	-	0.146	0.11		1129	
	noble metal	silver	7440-22-4	0.489	0.38	0.49	3779	4908
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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